

IN THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-10 (Canceled).

Claim 11 (Original) A method of manufacturing a semiconductor device comprising:
forming a first gate electrode on a first semiconductor layer in a first region of a semiconductor substrate, and a second gate electrode on a second semiconductor layer in a second region of the semiconductor substrate;
forming a first diffusion layer in said first semiconductor layer using said first gate electrode as a mask, and a second diffusion layer in said second semiconductor layer using said second gate electrode as a mask; and
selectively forming an epitaxial layer only on said first diffusion layer.

Claim 12 (Original) The method of manufacturing a semiconductor device according to claim 11, wherein said first region is an SOI region, and said second region is a bulk region.

Claim 13 (Original) The method of manufacturing a semiconductor device according to claim 11, wherein said selective forming of the epitaxial layer includes:
forming an oxide layer on the surface of said second diffusion layer in said second region by emitting O₂ plasma with only said first region being masked; and
subsequently forming said epitaxial layer by epitaxial growth on said first diffusion layer.

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Claim 14 (Original) The method of manufacturing a semiconductor device according to claim 11, further including:

implanting carbon into said first and second diffusion layers before forming said epitaxial layer,

wherein said selective forming of the epitaxial layer includes:

forming an oxide layer on the surface of said first diffusion layer in said first region by emitting O₂ plasma with only said second region being masked;

removing the mask, and then removing said oxide layer; and

subsequently forming said epitaxial layer by epitaxial growth on said first diffusion layer.

Claim 15 (Original) The method of manufacturing a semiconductor device according to claim 14, wherein said implanting carbon is performed by forming first and second gate sidewalls at side portions of said first and second gate electrodes through the RIE method using carbon gas as an active gas.

Claim 16 (Original) The method of manufacturing a semiconductor device according to claim 11, further including forming silicide layer by performing silicidation of the surface of said epitaxial layer on said first diffusion layer and said second diffusion layer.

Claim 17 (Original) The method of manufacturing a semiconductor device according to claim 11, including further forming an epitaxial layer on said first diffusion layer and forming an epitaxial layer on said second diffusion layer by the epitaxial growth method.

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Claim 18 (Original) The method of manufacturing a semiconductor device according to claim 17, further including performing silicidation of said epitaxial layers on said first diffusion layer and said second diffusion layer.

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